



Product/Process Change Notice - PCN 12_0299 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: TMP17 Mask Revision
Publication Date: 03-Dec-2012
Effectivity Date: 03-Mar-2013 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

The layout of one resistor was modified to optimize the TMP17 performance to the wafer fab process. Only the resistor and metal mask were changed. No schematic design changes were made to the device.

A polyimide layer was also added on top of the existing glassivation layer.

Reason For Change

As part of ADI's ongoing Continuous Improvement Program, ADI is implementing the change to improve the manufacturability of the TMP17, which will result in more predictable delivery to our customers.

The polyimide addition to the TMP17 offers the following advantages: improved ESD robustness, enhanced protection against die scratches, package stresses, Surface ESD/EOS events and radiation.

Numerous ADI products have always had a polyimide passivation layer on top of the glassivation layer. These products have proven highly reliable through numerous qualifications and many years of field application.

Impact of the change (positive or negative) on fit, form, function & reliability

This change will have no impact on the electrical performance, form, fit, or function of the device.

Summary of Supporting Information

Full wafer level test and final package test Cpk analysis was performed and all parameters were the same or better than current production material.

In addition, qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_12_0299_Rev_-_Qual Summary.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (6)

TMP17 / TMP17FS	TMP17 / TMP17FSZ	TMP17 / TMP17FSZ-RL	TMP17 / TMP17GS	TMP17 / TMP17GSZ
TMP17 / TMP17GSZ-RL				

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	03-Dec-2012	03-Mar-2013	Initial Release

Analog Devices, Inc.

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